

Thin Core Laminate for Multilayer/多層電路板用薄內層板材

KB-6150/6160 FR-4 纖維板

■ Features

- ◆ Excellent adhesive strength between layer
- ◆ Good dimensional stability
- ◆ Less resin smear in high speed drilling
- ◆ Good electrical and mechanical properties
- ◆ Excellent heat resistance

■ 特點

- ◆ 層之間的黏接性強
- ◆ 尺寸變化小
- ◆ 高速鑽孔時產生的樹脂污垢少
- ◆ 具有卓越的電氣及機械性能
- ◆ 優越的耐熱性

■ Applications / 用途

Mobile phone, Computer, Instrumentation, Military hard-ware, Guidance systems etc.

移動電話、計算機、檢測設備、錄像機、電視機、軍用裝備、導向系統等。

STANDARD PANEL SIZE 標準尺寸(mm)	COPPER FOIL THICKNESS 銅箔厚度	MANUFACTURING THICKNESS 制造厚度 (the copper foil thickness is excluded 不包括銅箔厚度)	THICKNESS TOLERANCE 厚度公差
914x1220 1020x1220 1041x1245 1067x1220	18 μ m	3mils (0.076mm)	± 0.7 mils (± 0.018 mm)
		4mils (0.10mm)	± 0.7 mils (± 0.018 mm)
		5mils (0.13mm)	± 1.0 mils (± 0.025 mm)
		6mils (0.15mm)	± 1.0 mils (± 0.025 mm)
	35 μ m	7mils (0.18mm)	± 1.5 mils (± 0.038 mm)
		8mils (0.20mm)	± 1.5 mils (± 0.038 mm)
		10mils (0.25mm)	± 1.5 mils (± 0.038 mm)
		12mils (0.30mm)	± 1.5 mils (± 0.038 mm)
	70 μ m	14mils (0.36mm)	± 2.0 mils (± 0.05 mm)
		15mils (0.38mm)	± 2.0 mils (± 0.05 mm)
		16mils (0.40mm)	± 2.0 mils (± 0.05 mm)

※ Other sheet size and thickness could be available upon request

※ 其它尺寸和厚度產品由用戶要求供應。